



Docket No.: 251598US0

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313



P.C.

ATTORNEYS AT LAW

RE: Application Serial No.: 10/820,123

Applicants: Yukio HOSAKA, et al.

Filing Date: April 8, 2004

For: ABRASIVE PAD, METHOD AND METAL MOLD
FOR MANUFACTURING THE SAME, AND
SEMICONDUCTOR WAFER POLISHING METHOD

Group Art Unit: 3723

Examiner: RACHUBA, MAURINA T.

SIR:

Attached hereto for filing are the following papers:

Response

Our check in the amount of **\$0.00** is attached covering any required fees. In the event any variance exists between the amount enclosed and the Patent Office charges for filing the above-noted documents, including any fees required under 37 C.F.R. 1.136 for any necessary Extension of Time to make the filing of the attached documents timely, please charge or credit the difference to our Deposit Account No. 15-0030. Further, if these papers are not considered timely filed, then a petition is hereby made under 37 C.F.R. 1.136 for the necessary extension of time. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

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IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF

YUKIO HOSAKA, ET AL.

: EXAMINER: RACHUBA, M.

SERIAL NO: 10/820,123

:

FILED: APRIL 8, 2004

: GROUP ART UNIT: 3723

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RESPONSE

COMMISSIONER FOR PATENTS
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SIR:

This is responsive to the Restriction Requirement mailed January 26, 2006.

Applicants elect, with traverse, the claims of Group I, Claims 1-6, 10 and 11, for examination.

Applicants further elect as the species for examination purposes only, species 1, Figures 1-8.

Claims 1-6, 10 and 11 are readable on the elected species.

Remarks/Arguments begin on page 2 of this paper.